

Procedural Review Voting Sheet

Editorial Change(s) to a published Standard or Safety Guideline (Independently from a Letter Ballot)

REGION/LOCALE: **North America**

GLOBAL TECHNICAL COMMITTEE: **3D Packaging & Integration**

EVENT: **NA Summer Meetings**

DATE OF MEETING: **07/15/2021**

PLACE OF MEETING: **OVTCCM**

TC CHAPTER CO-CHAIRS: **Bill Kerr/Evergreen Enhancement, Chris Moore/Covalent Metrology**

SEMI STANDARDS STAFF: **Laura Nguyen**

I. Document Title

Document Title

SEMI 3D4-0915, Guide for Metrology for Measuring Thickness, Total Thickness Variation (TTV), Bow, Warp/Sori, and Flatness of Bonded Wafer Stacks

II. Type 2 Editorial Change

Editorial changes that meet the requirements of the Regulations (see *Regulations* ¶¶ 8.9.4 & 8.9.5) are approved by a simple majority vote in a regularly scheduled meeting of the TC Chapter. [See PM 2.11.4]

Original section/paragraph number and at least one full sentence are required in “FROM” and “TO” fields.

	FROM: Section/Paragraph 4
	4 Referenced Standards and Documents 4.1 <i>SEMI Standards and Safety Guidelines</i>
1	NOTE 1: The SEMI 3DS-IC Global Technical Committee is developing a Guide for Describing Material Properties for a 300 mm 3DS-IC Wafer Stack intended to be used in conjunction with this Document. SEMI HB1 — Specifications for Sapphire Wafers Intended for Use for Manufacturing High Brightness-Light Emitting Diode Devices SEMI M78 — Guide for Reporting Wafer Nanotopography of Unpatterned Silicon Wafers for the 130 nm to 22 nm Generations in High Volume Manufacturing

TO: Section/Paragraph 4 4 Referenced Standards and Documents 4.1 <i>SEMI Standards and Safety Guidelines</i> NOTE 1: The SEMI 3DS-IC Global Technical Committee is developing a SEMI 3D9 — Guide for Describing Material Properties for a 300 mm 3DS-IC Wafer Stack intended to be used in conjunction with this Document. SEMI HB1 — Specifications for Sapphire Wafers Intended for Use for Manufacturing High Brightness-Light Emitting Diode Devices SEMI M78 — Guide for Determining Reporting Wafer Nanotopography of Unpatterned Silicon Wafers for the 130 nm to 22 nm Generations in High Volume Manufacturing	
Justification: (If necessary) Delete and correct Note 1 and fix outdated titles in Referenced Standards and Documents section.	
Motion	To approve the above editorial change(s).
Motion by/ 2nd by	By: Richard Allen / NIST - National Institute of Standards & Technology Second: Steve Martell / Nordson SONOSCAN
Discussion	None
Vote	6 Y 0 N ; If Y > 50% Motion passes , GO TO III

III. Safety Check

Note: See Regulations § 15 for further information.

Motion	X	This is not a Safety Document , when all safety-related information is removed, the Document is still technically sound and complete. (<i>Regulations ¶ 8.7.1</i>)
		This is a Safety Document , when all safety-related information is removed, the Document is not technically sound and complete. (<i>Regulations ¶ 8.7.2</i>)
		Safety Checklist (<i>Regulations ¶ 15.3</i>) is complete and has been included with the Document throughout the balloting process. (<i>Regulations ¶ 15.1.2</i>)
Motion by/2nd by		By: Steve Martell / Nordson SONOSCAN Second: Ilona Schmidt / Corning Inc.
Discussion		None
Vote		6 Y 0 N; Motion passed .

IV. Intellectual Property Check

Note: This Document may cover all or part of a Standard or Safety Guideline. Regardless of the coverage, this IP check applies to the entire Standard or Safety Guideline*. See *Regulations* § 16 for further information.

X	The TC Chapter meeting chair asked those participating, if they were aware of any patented technology that might be relevant (see <i>Regulations</i> ¶ 16.3.1.1) to the Standard or Safety Guideline; or, any copyrighted items or trademarks that are used/reproduced (see <i>Regulations</i> ¶ 16.4.1.2) in the Standard or Safety Guideline. (Also see, <i>Regulations</i> § 8.8)		
	X	The question is NOT answered in affirmative (No potentially material patented technology or use/reproduction of copyrighted items/trademarks is known.)	GO TO SECTION V.

V. Action for this Document

Motion	X	This Editorial Change Type 2 passed TC Chapter review and will be forwarded to the ISC A&R SC for procedural review.	
Motion by/ 2nd by		By: Steve Martell / Nordson SONOSCAN Second: Gregory Arslanian / Air Products	
Discussion		None	
Vote		6 Y 0 N; Motion passed.	
Final Action		X	Motion passed
			Motion failed